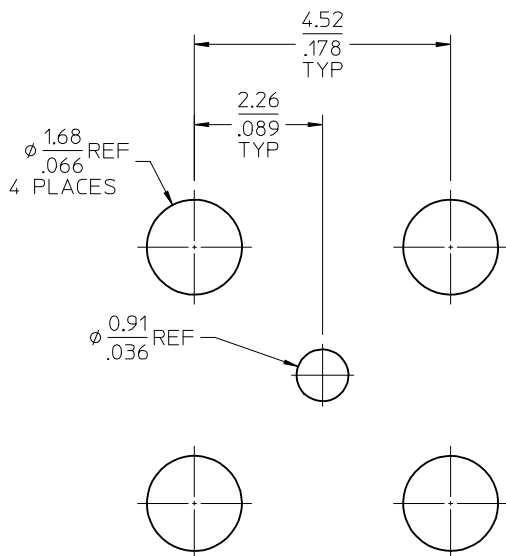
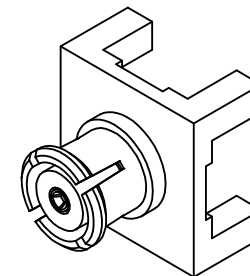


MATERIALS AND FINISHES:

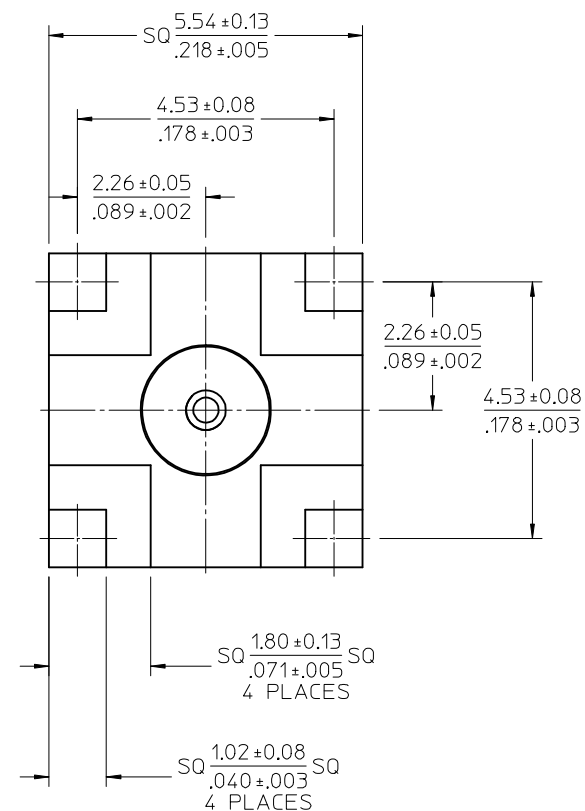
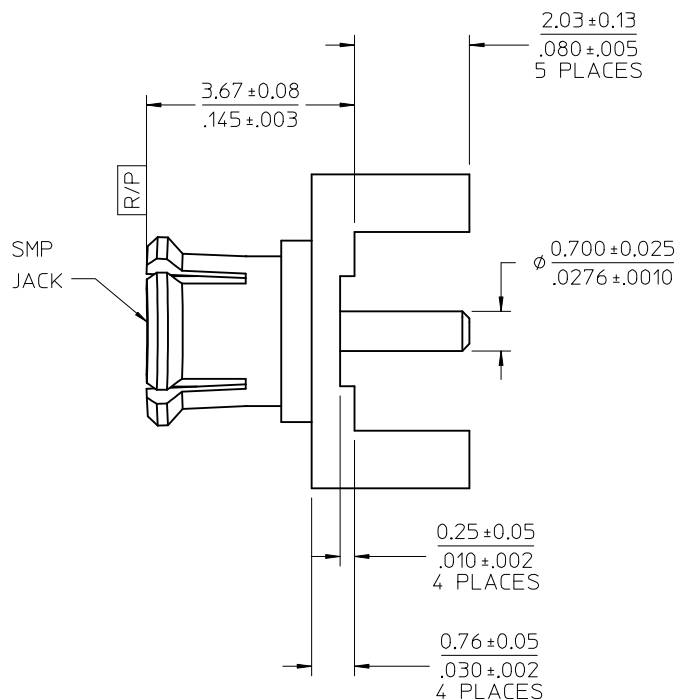
BODY: BERYLLIUM COPPER
 PLATED: GOLD (10μ-in MIN)
 OVER NICKEL (100μ-in MIN)

CENTER CONTACT: BERYLLIUM COPPER
 PLATED: GOLD (20μ-in MIN)
 OVER NICKEL (50μ-in MIN)

INSULATOR: PTFE



RECOMMENDED PCB LAYOUT



PART # 73406-6360

PS-89675-3320	PRODUCT SPECIFICATION
MIL-STD-348B, FIG. 326.1	INTERFACE SMP JACK
SPECIFICATION	DESCRIPTION

CHG: ADD TOLERANCE TO DIM 3.67/145 IN G8 ZONE. UPD MATERIALS AND FINISHES NOTE. DRWN: APRAKASHO1 2017/05/26 CHYKD: HBB 2017/05/26 IAPPR: AROBERTSON 2017/06/28

QUALITY SYMBOLS
▽=0
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± .010
2 PLACES ± 0.25	± ---
1 PLACE ± ---	± ---
0 PLACE ± ---	± ---
ANGULAR ± 2 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM/IN	
DRAWN BY	DATE
JWIENER	2012/06/18
CHECKED BY	DATE
SSS	2012/06/18
APPROVED BY	DATE
JWIENER	2012/06/26

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	METRIC	☉
TITLE		
SMP JACK PCB TH		
50 OHMS		
SMP-J/PCB EWR-4989		
molex		
MATERIAL NO.	DOCUMENT NO.	SHEET NO.
734066360	SD-73406-636	1 OF 1
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